

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5432471

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
XIAOXIA ZHANG	03/07/2019
KAPIL BHATTAD	03/08/2019
JING SUN	03/07/2019
QINGJIANG TIAN	03/08/2019
SRINIVAS YERRAMALLI	03/19/2019
TAMER KADOUS	03/13/2019
YONGBIN WEI	03/13/2019
ALEKSANDAR DAMNJANOVIC	03/19/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	QUALCOMM INCORPORATED
<b>Street Address:</b>	5775 MOREHOUSE DRIVE
<b>City:</b>	SAN DEIGO
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	92121-1714
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16241747
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	9727398641
<b>Email:</b>	ipdocketing@haynesboone.com, sidney.buchanan@haynesboone.com
<b>Correspondent Name:</b>	HAYNES AND BOONE LLP
<b>Address Line 1:</b>	2323 VICTORY AVENUE
<b>Address Line 2:</b>	SUITE 700
<b>Address Line 4:</b>	DALLAS, TEXAS 75219
<b>ATTORNEY DOCKET NUMBER:</b>	49606.517US01 - 181378
<b>NAME OF SUBMITTER:</b>	GREGORY P. WEBB

<b>SIGNATURE:</b>	/GREGORY P. WEBB/
<b>DATE SIGNED:</b>	03/20/2019
<b>Total Attachments: 9</b> source=49606.517US01 - Inventor's Executed Declarations#page1.tif source=49606.517US01 - Inventor's Executed Declarations#page2.tif source=49606.517US01 - Inventor's Executed Declarations#page3.tif source=49606.517US01 - Inventor's Executed Declarations#page4.tif source=49606.517US01 - Inventor's Executed Declarations#page5.tif source=49606.517US01 - Inventor's Executed Declarations#page6.tif source=49606.517US01 - Inventor's Executed Declarations#page7.tif source=49606.517US01 - Inventor's Executed Declarations#page8.tif source=49606.517US01 - Inventor's Executed Declarations#page9.tif	

ASSIGNMENT

WHEREAS, WE,

1. Xiaoxia ZHANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
2. Kapil BHATTAD, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
3. Jing SUN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
4. Qingjiang TIAN, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
5. Srinivas YERRAMALLI, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
6. Tamer KADOUS, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
7. Yongbin WEI, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
8. Aleksandar DAMNJANOVIC, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ADAPTIVE AUTONOMOUS UPLINK COMMUNICATION DESIGN** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have

been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 16/241,747 filed January 7, 2019, Qualcomm Reference No. 181378, and all provisional applications relating thereto, together with Indian Patent Application No(s). 201841002660, filed January 23, 2018, Qualcomm Reference No. 181378IN1, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;


AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;


AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 03/07/2019  
LOCATION DATE  
  
Xiaoxia ZHANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE  
Kapil BHATTAD

Done at San Diego, on 3/7/19  
LOCATION DATE  
  
Jing SUN

Done at San Diego, on 03/08/19  
LOCATION DATE  
  
Qingjiang TIAN

Done at San Diego, on 03/19/19  
LOCATION DATE  
  
Srinivas YERRAMALLI

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE  
Tamer KADOUS

Done at San Diego, on 3/13/19  
LOCATION DATE  
  
Yongbin WEI

Done at San Diego, on 3/19/19  
LOCATION DATE  
  
Aleksandar DAMNJANOVIC

**ASSIGNMENT**

WHEREAS, WE,

1. Xiaoxia ZHANG, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
2. Kapil BHATTAD, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,
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8. Aleksandar DAMNJANOVIC, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ADAPTIVE AUTONOMOUS UPLINK COMMUNICATION DESIGN** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have

been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 16/241,747 filed January 7, 2019, Qualcomm Reference No. 181378, and all provisional applications relating thereto, together with Indian Patent Application No(s). 201841002660, filed January 23, 2018, Qualcomm Reference No. 181378IN1, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Xiaoxia ZHANG

Done at Bengaluru, on 03/08/2019  
LOCATION DATE Kapil  
Kapil BHATTAD

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Jing SUN

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Qingjiang TIAN

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Srinivas YERRAMALLI

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Tamer KADOUS

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Yongbin WEI

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Aleksandar DAMNJANOVIC



ASSIGNMENT

WHEREAS, WE,

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8. Aleksandar DAMNJANOVIC, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714,

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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.


Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Xiaoxia ZHANG

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Kapil BHATTAD

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Jing SUN

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Qingjiang TIAN

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Srinivas YERRAMALLI

Done at San Diego, on 03-13-19  
LOCATION DATE   
Tamer KADOUS

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Yongbin WEI

Done at \_\_\_\_\_, on \_\_\_\_\_  
LOCATION DATE Aleksandar DAMNJANOVIC